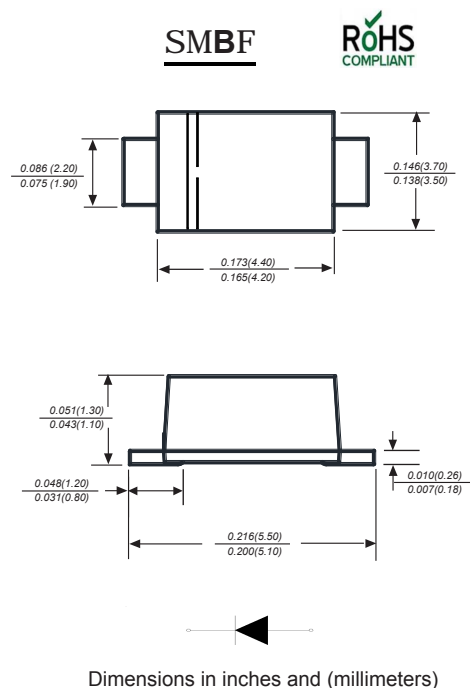


## SURFACE MOUNT SCHOTTKY BARRIER RECTIFIER

### Features

- ◆ Metal silicon junction, majority carrier conduction For surface mounted applications
- ◆ Low power loss,high efficiency
- ◆ High forward surge current capability
- ◆ For use in low voltage,high frequency inverters, free wheeling,and polarity protection applcatlons



### Mechanical Data

Case: JEDEC UT BØ molded plastic body

Terminals: Solderable per MIL-STD-750, Method 2026A

Polarity: Polarity symbol marking on body Mounting

Position: Any

Weight : 0.002 ounce, 0.057 grams

### Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	SS32BF	SS33BF	SS34BF	SS35BF	SS36BF	SS38BF	SS310BF	SS315BF	SS320BF	UNITS
		MDD S32B	MDD S33B	MDD S34B	MDD S35B	MDD S36B	MDD S38B	MDD S310B	MDD S315B	MDD S320B	
Maximum repetitive peak reverse voltage	$V_{RRM}$	20	30	40	50	60	80	100	150	200	V
Maximum RMS voltage	$V_{RMS}$	14	21	28	35	42	56	70	105	140	V
Maximum DC blocking voltage	$V_{DC}$	20	30	40	50	60	80	100	150	200	V
Maximum average forward rectified current	$I_{(AV)}$	3.0									A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	80									A
Maximum instantaneous forward voltage at 3.0A	$V_F$	0.55			0.70		0.85		0.95		V
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=100^\circ\text{C}$	$I_R$	0.5			5.0		0.3		3.0		mA
Typical junction capacitance (NOTE 1)	$C_J$	450					400				pF
Typical thermal resistance (NOTE 2)	$R_{\theta JA}$	65									$^\circ\text{C}/\text{W}$
Operating junction temperature range	$T_J$	-55 to +125									$^\circ\text{C}$
Storage temperature range	$T_{STG}$	-55 to +150									$^\circ\text{C}$

**Note:** 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

2. P.C.B. mounted with 2.0"x2.0" (5.0x5.0cm) copper pad areas

## Typical Characteristics

Fig.1 Forward Current Derating Curve

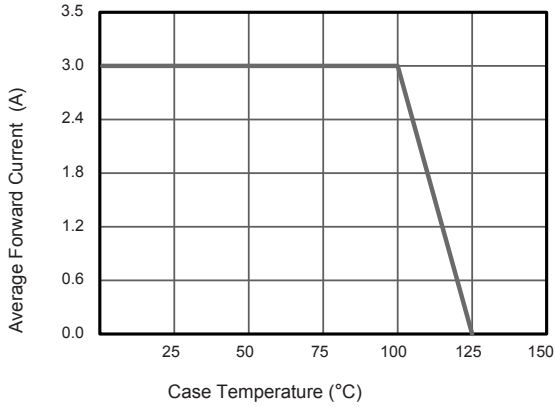


Fig.2 Typical Reverse Characteristics

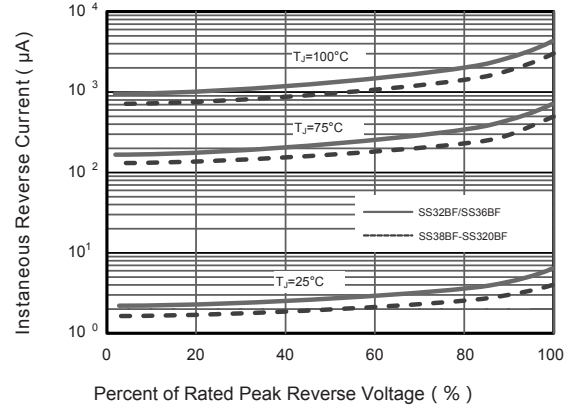


Fig.3 Typical Forward Characteristic

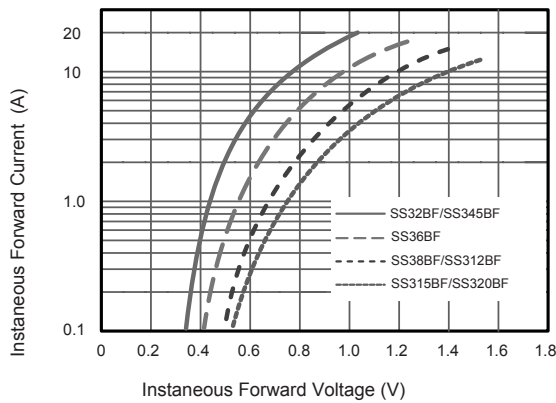


Fig.4 Typical Junction Capacitance

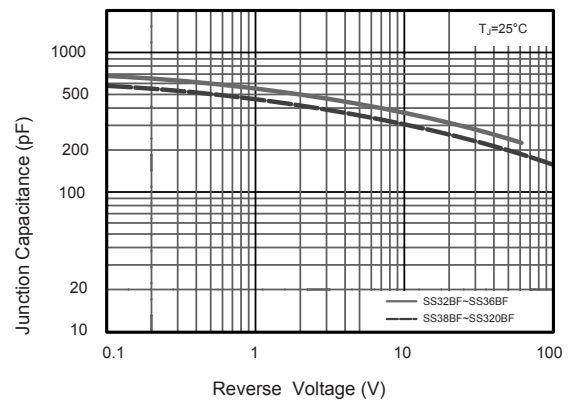


Fig.5 Maximum Non-Repetitive Forward Surge Current

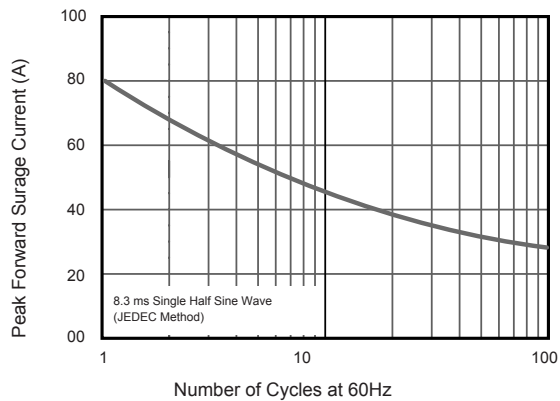
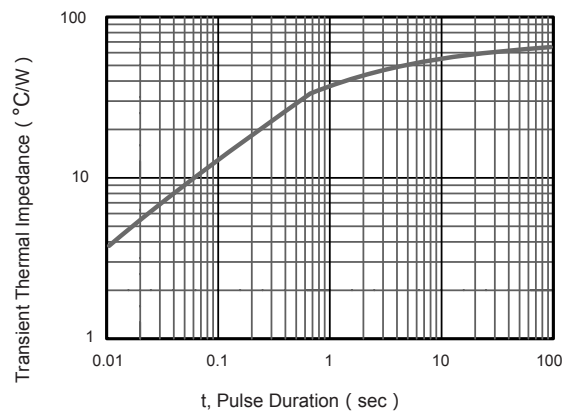
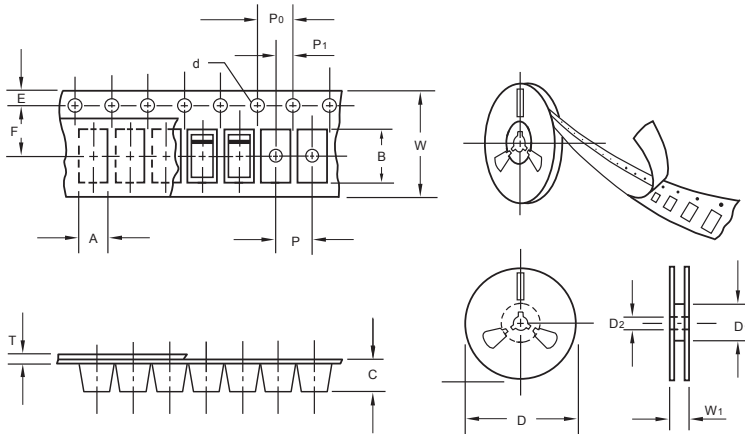


Fig.6- Typical Transient Thermal Impedance



The curve above is for reference only.

## Packing information



unit:mm

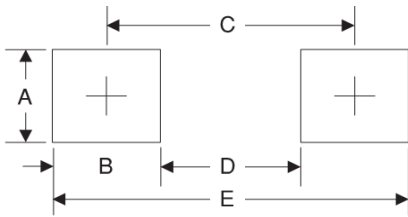
Item	Symbol	Tolerance	SMBF
Carrier width	A	0.1	3.81
Carrier length	B	0.1	5.61
Carrier depth	C	0.1	1.60
Sprocket hole	d	0.05	1.50
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D <sub>1</sub>	min	50.00
Feed hole diameter	D <sub>2</sub>	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	5.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P <sub>0</sub>	0.1	4.00
Embossment center	P <sub>1</sub>	0.1	2.00
Overall tape thickness	T	0.1	0.30
Tape width	W	0.3	12.00
Reel width	W <sub>1</sub>	1.0	12.30

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

## Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (mm)	BOX (pcs)	INNER BOX (mm)	REEL DIA. (mm)	CARTON SIZE (mm)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMBF	13"	5,000	4.0	10,000	190*190*41	330	365*365*360	80,000	14.0

## Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	2.54	0.100
B	1.8	0.071
C	4.8	0.189
D	3.0	0.118
E	6.6	0.260